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06-26-2002



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Atty Docket No: SEL 197

IN THE UNITED STATES PAT	TENT AND TRADEMARK OF FIGURE THE STATE OF TH
n re application of: Shunpei YAMAZAKI et al Serial No: 09/618,930 Siled: July 18, 2000 For: SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF Art Unit: 2818 Examiner: Phuc T. Dang Open School of the property of the pr	is being deposited with the United State Postal Service as first class mail in a envelope addressed to: Commissioner for Patents, Washington D.C. 20231, on
PATENT ASSIGNMENT	MENT COVER SHEET
Commissioner for Patents Washington, D. C. 20231 Off-//-00 Sir:	Date: June13, 2002
Please record the attached original document or copy th	
1a. Name of Conveying Party(ies): Shunpei YAMAZAKI; Hideomi SUZAWA; Koji ONO; and Yasuyuki ARAI 1b. Name of Conveying Party(ies): 2a. Name and Address of Receiving Party(ies): Name: Semiconductor Energy Laboratory Co., Ltd. Address: 398 Hase, Atsugi-shi, Kanagawa-ken 243-0036 JAPAN 2b. Name and Address of Receiving Party(ies): Name: Address 3. Nature of Conveyance X Assignment Merger Security Agreement Change of Name Other X Execution Date: June 30, 2000 and July 3, 2000 4. Application Number(s) or Patent number(s) (If this document is being filed together with a new application, the execution date of the application is: 4a. Patent Application No.(s) 09/618,930 4b. Patent No.(s)	5. Name and Address of Party to Whom Correspondence Concerning Document Should be Mailed: Stephen B. Heller COOK, ALEX, McFARRON, MANZO, CUMMINGS & MEHLER, LTD. 200 West Adams Street, Suite 2850 Chicago, Illinois 60606 6. Total Number of Applications and Patents Involved: _1 7. Total Fee (37 CFR 3.41): \$40.00
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Atty Docket No: SEL 197

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In re application of: Shunpei Yamazaki et al.	Date of DepositJuly 18, 2000
Serial No: Filed: Herewith	
For: Semiconductor Device And Manufacturing Method Thereo Art Unit: Examiner:	("Express Mail Post Office to Addressee" service
PATENT ASSIGNM	and is addressed to the Assistant Comm sounder MENT COVER STREET ents, Washington, D.C. 20231
Assistant Commissioner for Patents Washington, D. C. 20231	Name Nathan Wollack July 11, 2000
Sir: Please record the attached original document or copy the	(in ped or printed) Nathan Wolfan nereof. Total numing the Bages (with cover sheet): 2
1. Name of Conveying Party(ies): Shunpei YAMAZAKI, Hideomi SUZAWA, Koji ONO and Yasuyuki ARAI 2a. Name and Address of Receiving Party(ies): Name: Semiconductor Energy Laboratory Co., Ltd. Address: 398, Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan 2b. Name and Address of Receiving Party(ies): Name: Address Address	5. Name and Address of Party to Whom Correspondence Concerning Document Should be Mailed: Edward D. Manzo, Esq. COOK, ALEX, McFARRON, MANZO, CUMMINGS & MEHLER, LTD. 200 West Adams Street, Suite 2850 Chicago, Illinois 60606 6. Total Number of Applications and Patents Involved: 1
3. Nature of Conveyance X Assignment Merger Security Agreement Change of Name Other X Execution Date: 6/30/2000; 7/3/00 4. Application Number(s) or Patent number(s) (If this document is being filed together with a new application, the execution date of the application is: 6/30/00; 7/3/00) 4a. Patent Application No.(s) 4b. Patent No.(s)	7. Total Fee (37 CFR 3.41): \$40.00 7a. X Enclosed 7b. X Authorized to be Charged to Deposit Account For Any Deficiency 8. Deposit Account Number: 50/1039 (A duplicate copy of this page is attached) 9. Statement and Signature: To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Mark J. Murphy Name of Person Signing Signature Reg. No. 34,225 Date: July 11, 2000

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ASSIGNMENT

Identity Of The Patent Application.	I am the inventor (or one joint inventor) of a patent applicatio	n
that I am assigning. The patent applic	cation I am assigning is entitled SEMICONDUCTOR DEVICE	F
AND MANUFACTURING METHOD	THEREOF which I executed herewith. If the patent application	= n
has already been filed, it received so	serial numberand bears a filing date of	

The Assignee and The Assignment. I assign my patent rights to Semiconductor Energy Laboratory Co., Ltd. a corporation organized according to the laws of <u>Japan</u>, having a place of business at <u>398</u>, <u>Hase</u>, Atsugi-shi, Kanagawa-ken 243-0036 Japan (hereinafter "the Assignee"). The rights I assign are my entire right, title and interest in the invention or improvements disclosed in the patent application and any and all other applications for United States Letters Patent which I may file, either solely or jointly with others, on the invention or improvements, including all continuations, divisionals, and continuations-in-part, and in any and all United States Letters Patent which may be obtained on any of said applications, and in any reissue or extension thereof. I also assign to the Assignee all priority rights under the International Convention. I agree to execute, at the request of the Assignee, all documents in connection with any application for United States letters patent therefor.

Payment Received. I am making this assignment in consideration of One Dollar and other good and valuable consideration. I acknowledge the receipt and sufficiency of the consideration.

Authorizations. I request the U.S. Commissioner of Patents and Trademarks to issue the Letters Patent to the Assignee. I authorize the attorney(s) of record in the application to insert in this assignment document the date and serial number of the application.

Further Acts. I agree, upon the request and at the expense of the Assignee, to execute any divisional, continuation or substitute application for the invention or improvements, and any oath, declaration or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon the application. I agree to perform, upon request, any affirmative acts to obtain said Letters Patent of the United States and to vest in the Assignee all rights therein, so that the Letters Patent will be held and enjoyed by the Assignee, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me if this assignment had not been made.

Interference. In the event that any application or Letters Patent that I now assign becomes involved in interference, I agree to cooperate to the best of my ability in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof.

RECORDED: 07/11/2000

06/30/2000 Date

Name: Hidcomi SUZAWA

Name: Koji ONO

Name: Koji ONO

Date

07/03/2000

Date

07/03/2000

Date

PATENT REEL: 013014 FRAME: 0912